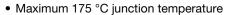


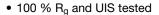
# VS4410AT-VB Datasheet N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY			
V <sub>DS</sub> (V)	100		
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0. 005		
I <sub>D</sub> (A) <sup>a</sup>	120		
Configuration	Single		

#### **FEATURES**



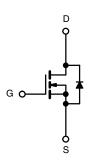




• Material categorization: for definitions of compliance please see







N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage	V <sub>DS</sub>	100	V		
Gate-Source Voltage	V <sub>GS</sub>	± 20			
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C	,	120 <sup>d</sup>		
	T <sub>C</sub> = 70 °C	I <sub>D</sub>	90 <sup>d</sup>		
Pulsed Drain Current (t = 100 μs)	I <sub>DM</sub>	480	А		
Avalanche Current		I <sub>AS</sub>	I <sub>AS</sub> 73		
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	266	mJ	
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C	Б	370 b	· W	
	T <sub>C</sub> = 125 °C	P <sub>D</sub>	120 <sup>b</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	LIMIT	UNIT	
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	40	°C/W	
Junction-to-Case (Drain)	$R_{thJC}$	0.4	C/VV	

### Notes

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR4 material).
- d. Package limited.



PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static				1			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ 100 -		-	-	V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2.5	-	4	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 250	nA	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V	-	-	1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	150	μA	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C	-	-	5	mA	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	120	-	-	Α	
Drain-Source On-State Resistance <sup>a</sup>	D	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A	-	0.005	-	Ω	
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 7.5 V, I <sub>D</sub> = 15 A	-	0.006	-		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A	-	82	-	S	
Dynamic <sup>b</sup>				•			
Input Capacitance	C <sub>iss</sub>		-	10000	-	pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 50 \text{ V}, f = 1 \text{ MHz}$	-	2025	-		
Reverse Transfer Capacitance	C <sub>rss</sub>		-	165	-		
Total Gate Charge <sup>c</sup>	Qg		-	76	120		
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	-	23	-	nC	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$		-	17	-		
Gate Resistance	$R_g$	f = 1 MHz	0.6	3.3	6.6	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>		-	15	30		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 50 V, $R_L$ = 5 $\Omega$	-	22	40		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	55	100	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>		-	15	30		
Drain-Source Body Diode Ratings ar	nd Characteri	stics <sup>b</sup> (T <sub>C</sub> = 25 °C)		•			
Pulsed Current	I <sub>SM</sub>		-	-	480	Α	
Forward Voltage <sup>a</sup>	$V_{SD}$	I <sub>F</sub> = 10 A, V <sub>GS</sub> = 0 V	-	0.8	1.5	V	

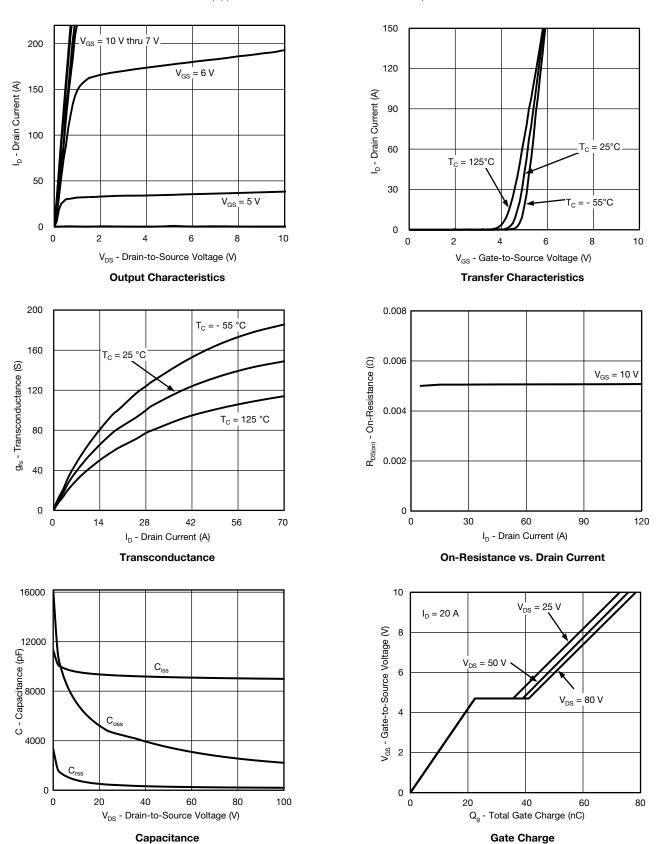
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

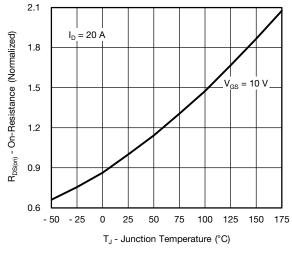


# TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)

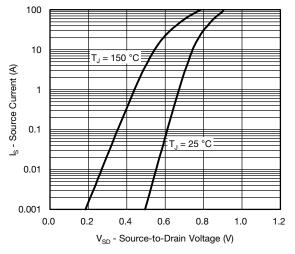




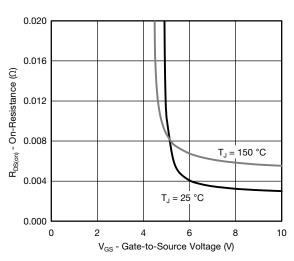
# TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



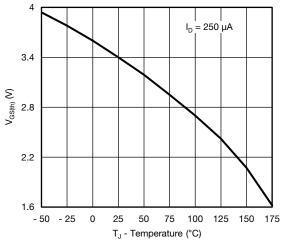
On-Resistance vs. Junction Temperature



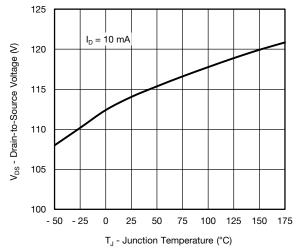
Source Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



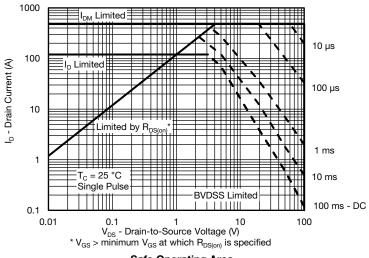
**Threshold Voltage** 



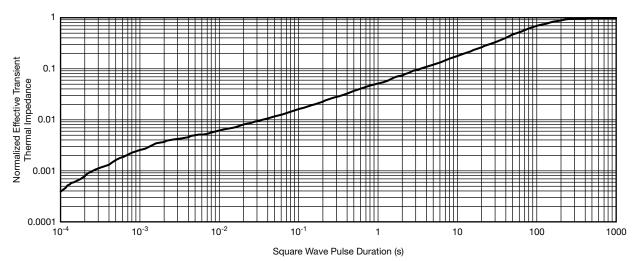
**Drain Source Breakdown vs. Junction Temperature** 



# **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



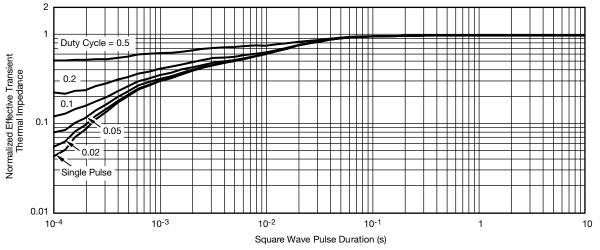
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



## **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

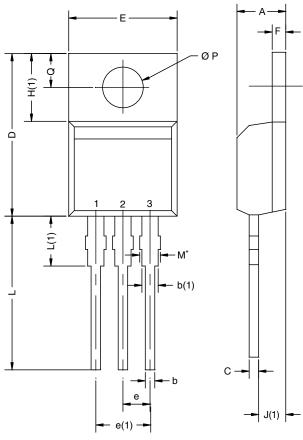
#### Note

- The characteristics shown in the two graphs
- Normalized Transient Thermal Impedance Junction to Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction to Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



# **TO-220AB**



1 -	l	
		D2

	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
D2	12.19	12.70	0.480	0.500	
E	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471					

#### Note

 $^{\star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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